

a first heat radiating pattern for conducting heat formed at a position on a front surface of said circuit board corresponding to said electronic component, such that the heat radiating plate of said electronic component is connected to said first heat radiating pattern by soldering;

a second heat radiating pattern for conducting heat formed at a position on a rear surface of said circuit board corresponding to said electronic component;

a plated layer to which said second heat radiating pattern is soldered; and

heat radiating means mounted at a position corresponding to said electronic component on the rear surface of said circuit board, such that said heat radiating means is mounted on said circuit board via said plated layer, wherein

said second heat radiating pattern has a larger area than that of said first heat radiating pattern.

---